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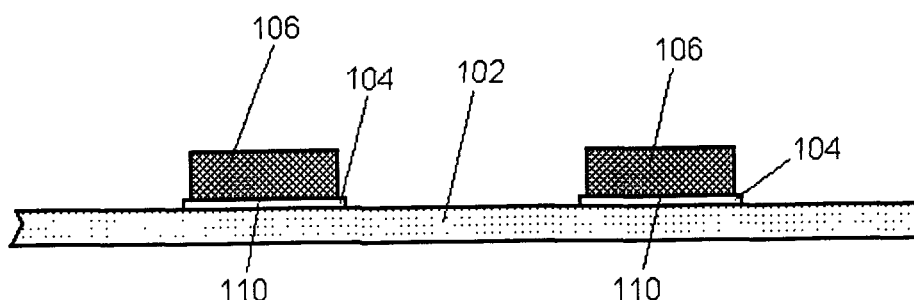
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(54) Title: MICROELECTRONIC PACKAGE HAVING AN INTEGRATED HEAT SINK AND BUILD-UP LAYERS



(57) Abstract: A microelectronic package fabrication technology that attaches at least one microelectronic die onto a heat spreader and encapsulates the microelectronic die/dice thereon which may further include a microelectronic packaging core abutting the heat spreader wherein the microelectronic die/dice reside within at least one opening in a microelectronic package core. After encapsulation, build-up layers may be fabricated to form electrical connections with the microelectronic die/dice.